

# STYCAST 2651MM CAT 24 LV

February 2017

## PRODUCT DESCRIPTION

STYCAST 2651MM CAT 24LV provides the following product characteristics:

|   |  |
|---|--|
| <b>Technology</b>                               | Epoxy  |
| <b>Appearance (Resin)</b>                       | Black  |
| <b>Mix Ratio, by weight - Material:Catalyst</b> | 100 : 15   |
| <b>Mix Ratio, by Volume - Material:Catalyst</b> | 100 : 24   |
| <b>Product Benefits</b>                         | <ul style="list-style-type: none"> <li>• General purpose</li> <li>• Low viscosity</li> <li>• Good machinability</li> <li>• Excellent thermal shock and impact resistance</li> <li>• Excellent low temperature properties</li> <li>• Excellent adhesion to glass</li> </ul> |
| <b>Operating Temperature - Continuous</b>       | -65 to +105°C  |
| <b>Operating Temperature - Intermittent</b>     | -65 to +120°C  |
| <b>Cure</b>                                     | Room temperature and Heat cure   |
| <b>Application</b>                              | Encapsulant  |

STYCAST 2651MM CAT 24LV is a general purpose encapsulant designed for machine dispensing and for parts requiring post molding machining.

STYCAST 2651MM can be used with a variety of catalysts. For more information on mixed properties when used with other available catalysts, please contact HITEK Electronic Materials

## TYPICAL PROPERTIES OF UNCURED MATERIAL

### Part A Properties STYCAST 2651MM

|                                     |        |
|-------------------------------------|--------|
| Viscosity, Brookfield , mPa·s (cP): |        |
| Spindle 5, speed 5 rpm              | 35,000 |
| Density, g/cm <sup>3</sup>          | 1.61   |
| Shelf Life @ 18 to 25°C, days       | 365    |
| Flash Point - See SDS               |        |

### Part B Properties CAT 24LV

|                               |      |
|-------------------------------|------|
| Viscosity @ 25 °C, mPa·s (cP) | 15   |
| Density, g/cm <sup>3</sup>    | 1.05 |
| Flash Point - See SDS         |      |

### Mixed Properties STYCAST 2651MM CAT 24LV

|                                      |    |
|--------------------------------------|----|
| Work Life, 100 grams @ 25°C, minutes | 30 |
| Flash Point - See SDS                |    |

## TYPICAL CURING PERFORMANCE

### Recommended Cure

|                        |
|------------------------|
| 24 hours @ 25°C        |
| 4 to 6 hours @ 45°C    |
| 2 to 4 minutes @ 65 °C |

For optimum performance, follow the initial cure with a post cure of 4 to 6 hours at the highest expected use temperature.

Alternate cure schedules may also be possible. Contact your Henkel representative for further information.

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

## TYPICAL PROPERTIES OF CURED MATERIAL

### Physical Properties

|  |  |
|--|--|
| Hardness, Shore D                          | 90   |
| Coefficient of Thermal Expansion , ppm/°C: |  |
| Below Tg                                   | 50   |
| Above Tg                                   | 133  |
| Glass Transition Temperature, °C:          |  |
| (Tg) by TMA                                | 45   |
| DMA, Tangent Delta                         | 74   |
| DMA, Onset Point                           | 61   |
| Young's modulus (E) :                      |  |
| @ 35°C                                     | N/mm <sup>2</sup> 6,623<br>(psi) (960,584) |
| @ 50°C                                     | N/mm <sup>2</sup> 6,091<br>(psi) (883,424) |
| @ 100°C                                    | N/mm <sup>2</sup> 54<br>(psi) (7,832)      |
| @ 150°C                                    | N/mm <sup>2</sup> 62<br>(psi) (8,992)      |
| Weight Loss :                              |  |
| @ 150°C                                    | 0.33                                       |
| @ 200°C                                    | 0.49                                       |
| @ 250°C                                    | 0.54                                       |
| @ 300°C                                    | 0.79                                       |
| @ 700°C                                    | 49.7                                       |
| Thermal Conductivity, W/(m-K)              | 0.6  |
| Linear Shrinkage, %                        | 0.72                                       |

|                       |      |
|-----------------------|------|
| Water Absorption:     |      |
| After 1 day @ RT      | 0.14 |
| After 7 days @ RT     | 0.39 |
| After 1 hour @ 100 °C | 0.55 |

**Electrical Properties**

|  |                      |
|--|----------------------|
| Volume Resistivity, ohm/cm                 | 1.9×10 <sup>15</sup> |
| Surface Resistivity, ohms                  | 1.8×10 <sup>15</sup> |
| Dielectric Constant / Dissipation Factor : |                      |
| @ 50 Hz                                    | 4.6/0.007            |
| @ 1 KHz                                    | 4.8/0.008            |
| @ 1 MHz                                    | 4.3/0.034            |

**GENERAL INFORMATION**

For safe handling information on this product, consult the Safety Data Sheet, (SDS).

**DIRECTIONS FOR USE**

1. Complete cleaning of the components and substrates should be performed to remove contamination such as dust, moisture, salt and oils which can cause electrical failure, poor adhesion or corrosion in an embedded part.
2. Some filler settling is common during shipping and storage. For this reason, it is recommended that the contents of the shipping container be thoroughly mixed prior to use.
3. Power mixing is preferred to ensure a homogeneous product.
4. Accurately weigh resin and hardener into a clean container in the recommended ratio. Weighing apparatus having an accuracy in proportion to the amounts being weighed should be used.
5. Blend components by hand, using a kneading motion, for 2 to 3 minutes. Scrape the bottom and sides of the mixing container frequently to produce a uniform mixture.
6. If possible, power mix for an additional 2 to 3 minutes. Avoid high mixing speeds. This can entrap excessive amounts of air. It can also cause overheating of the mixture, resulting in reduced working life.
7. To ensure a void-free embedment, vacuum deairing or degassing should be performed to remove any entrapped air introduced during the mixing operation.
8. Vacuum deair mixture at 1 to 5 mm mercury. The foam will rise several times the liquid height and then subside.
9. Continue vacuum deairing until most of the bubbling has ceased. This usually takes 3 to 10 minutes.
10. To facilitate deairing in difficult to deair materials, add a few drops of an air release agent, such as ANTIFOAM 88 into 100 grams of mixture.

11. Gentle warming will also help, but pot life will be shortened.
12. Pour mixture into cavity or mold.
13. Gentle warming of the mold or assembly reduces the viscosity. This improves the flow of the material into the unit having intricate shapes or tightly packed coils or components.
14. Further vacuum deairing in the mold may be required for critical applications.

**STORAGE:**

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

**Optimal Storage : 25 °C**

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

**Not for product specifications**

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

**Disclaimer****Note:**

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

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Reference 1

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